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# TROUBLESHOOTING MOLDING PROBLEMS

**Molding Guide for BMC & SMC** 

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#### **Blisters**

A blister is a delamination that produces a bulge on the surface of the part. This bulge is usually regular in shape and can range in size from 1/8 to 10 inches. A blister is caused by the presence of gases under pressure within the substrate, forcing the skin away from the glass. Can be seen on painted or unpainted parts.

Probable Cause		
Material	<ul> <li>Insufficient glass wet out with resin (dry glass)</li> <li>Foreign objects/contamination (film, flash, etc.) in or on the charge</li> <li>Wrinkles/pockets in discontinuous surface of SMC charge pattern</li> </ul>	
Process	<ul> <li>Adding small SMC pieces to charge pattern which trap air</li> <li>Insufficient pressure on SMC during cure cycle</li> <li>Oven temperature heat-up rate too fast, especially in combination with a high moisture content part</li> <li>Improper charge patter (too large, rolled or folded)</li> <li>Mold temperature out of spec</li> <li>Vacuum too low; improper vacuum cycle</li> <li>Low cure time (under cure)</li> <li>Press closure speed to fast (air trapped in laminate)</li> </ul>	
Tooling	<ul> <li>Mold shear edge is too tight (not allowing air to bleed out)</li> <li>Tool Deflection</li> </ul>	
<b>Corrective Action</b>		
Material	<ul> <li>Check for fiberglass wet out</li> <li>Check material for contaminants and check for moisture contamination</li> <li>Evaluate viscosity levels affect on blisters, look at high, medium and low</li> <li>Use less reactive catalyst</li> <li>Select different shrink additives</li> <li>Verify material is not dried out</li> </ul>	
Process	<ul> <li>Increase material flow distance</li> <li>Increase molding pressure</li> <li>Pyramid charge in center of the tool</li> <li>Load pattern, location, size, thickness</li> <li>Appropriate vacuum amount and timing (position)</li> <li>Appropriate press closure speeds</li> <li>Appropriate mold temperatures</li> <li>Appropriate cure time</li> <li>Do not use makeup pieces in the charge</li> <li>Be certain mold shears are clean with at least 0.004" of flash</li> </ul>	
Tooling	Check for mold deflection     Check for Platen parallelism	



# **Bond Failure**

Failure of a bonde	d assembly, usually at the interface of the adhesive and the substrate
Probable Cause	
Material	Out of spec SMC
Process	<ul> <li>Gel time of adhesive too short to permit proper bonding</li> </ul>
	<ul> <li>Bond not fully cured before clamps are removed</li> </ul>
	<ul> <li>Improperly prepared bond surfaces</li> </ul>
	<ul> <li>Mix ratio of the two-component adhesive is off</li> </ul>
	Moisture contamination of adhesive or surface to be bonded
	Out of spec adhesive
	• Excessive internal or external mold release in/on the SMC
	Shift between inner and outer panels during curing of the adhesive
	Incompatible substrate and bond material
	• Introduction of air into dispense system causing gaps, ratio variations
	Improper cure cycle
	Improper heating during bond cycle
Tooling	
<b>Corrective Action</b>	
Material	
Process	Improve QC of adhesive material
	• Fully cure adhesive before pressure or clamping is removed
	Properly prepare surfaces to be bonded
	<ul> <li>Ensure that periodic check of the mix ratio is performed</li> </ul>
	Control temperature of adhesive
	<ul> <li>Do no use external mold release on bond areas</li> </ul>
Tooling	



#### **Bond Readout**

Bond readout is a	surface distortion similar to a hump or sink that occurs over a bond line
Probable Cause	
Material	
Process	<ul> <li>Mismatch of compliance between outer panel, inner panel and adhesive</li> <li>Incompatible thermal expansion coefficients between the SMC and the adhesive</li> <li>Excessive shrinkage of the adhesive during the fixturing and curing cycles</li> <li>Excessive fixturing pressure induced due to part mismatch of the outer/inner panels and the bond line standoffs</li> <li>Excessive fixturing temperature due to non-uniform heating</li> <li>Hot spots from adhesive exothermic reaction due to non-uniform adhesive thickness</li> <li>Bond gap thick above 1.5 mm</li> <li>Outer panel thin, less than 2.0 mm</li> <li>Inner thickness above maximum</li> </ul>
Tooling	
<b>Corrective Action</b>	
Material	
Process	<ul> <li>Increase the thickness of the bonding area of the appearance panel or select a more flexible adhesive</li> <li>Match the thermal expansion coefficients between the substrate and the adhesive as much as possible</li> <li>Select an adhesive with minimum polymerization shrinkage</li> <li>Obtain matched outer/inner panels through better tooling</li> <li>Eliminate bond line standoffs</li> <li>Use closed-loop feedback temperature control system for tighter temperature variation tolerance of the fixture</li> <li>Minimize and control clamp pressure</li> <li>Mold warp-free parts; do not use adhesive bond fixture to straighten parts</li> <li>Check adhesive thickness to specification</li> <li>Check inner thickness to specification</li> </ul>
Tooling	



#### Chip

A chip is damage to the surface of the part that results in small (less than /2 inch) missing pieces. A chip usually occurs near the edge, and since it is nonstructural, it usually is repairable

Probable Cause	
Material	Resin-rich edge
Process	Rough handling
	Rough bypass
	<ul> <li>Shipping racks lack necessary padding</li> </ul>
	<ul> <li>No use of in-process racks (parts are stacked on each other)</li> </ul>
	<ul> <li>Squared edge on part at mating surface with adjacent parts</li> </ul>
Tooling	<ul> <li>Improperly designed secondary fixtures (non padded in all necessary areas)</li> </ul>
	Mold defects on edges or flash stuck to shear edge
<b>Corrective Action</b>	
Material	Increase compound viscosity
Process	Utilize transfer lines and other hands-off processing techniques
	Train workers in proper handling techniques
	<ul> <li>Improve shipping procedures and monitor part quality</li> </ul>
	Improve shipping rack repair procedures
	Add external mold release and clean
	Slow ejector speed
	Slow press closure rate
	Relocate charge
	Decrease molding pressure
Tooling	Design secondary fixtures properly and coat them with soft materials to absorb
	shocks
	<ul> <li>Preventative maintenance on molds and fixtures</li> </ul>
	<ul> <li>Periodically clean flash on shear edges and gummy deposits of styrene</li> </ul>
	Polish tool surface



# Contamination

Foreign material i	n the laminate
Probable Cause	
Material	Foreign material in SMC compound or raw materials
Process	<ul> <li>Foreign material from the molding presses</li> </ul>
Tooling	
<b>Corrective Action</b>	
Material	Check for foreign materials in molding compound and cut out if necessary
	Check for foreign materials in raw materials
Process	
Tooling	



# Crazing (Surface Cracks)

Craze cracks are hairline cracks that do not go through the entire thickness of the part. These cracks usually occur in groups. Craze cracks can appear similar to porosity on painted parts.

Probable Cause	
Material	
Process	Mechanical overstressing caused by part sticking in the mold or rough handling
	<ul> <li>Poor material flow pattern around mash-offs, core pins, mold outs</li> </ul>
	• Thermal stresses induced by mold temperature or by non-uniform part cool
	down
	Charge pattern changed by adding small pieces to make up weight
	• Ejector pins
	Thick-to-thin wall thickness variation
Tooling	Secondary fixtures improperly designed
	Thick-to-thin wall thickness variation
	Ribs too thick with respect to wall thickness
	Cored holes or slides too low from designated surface position
<b>Corrective Action</b>	
Material	
Process	Train workers in proper handling techniques
	Cool parts at a uniform rate
	Design charge pattern to minimize improper flow behavior
	Do not use makeup pieces in charge pattern
	Minimize mash-offs
	Slow ejection system to reduce ejector pin crazing
	<ul> <li>Increase differential temperature between core and cavity</li> </ul>
Tooling	<ul> <li>Design secondary fixtures so they do not induce stress on the part and coat</li> </ul>
	them with soft materials to absorb shock
	Polish shear edges of cavity, eliminate back draft or undercuts
	Ensure smooth transition from thick to thin sections



# Dieseling

Dieseling is a burn	It spot on the laminate, often accompanied by non-fills
Probable Cause	
Material	
Process	Air entrapped in the tool which burns
Tooling	
<b>Corrective Action</b>	
Material	
Process	Increase material flow distance
	Slow press closure
	Vary mold temperature differential
	Increase shear opening (assumes dieseling occurs near the shear edge
	Add vented ejector pins
Tooling	



#### Dirt

Dirt is a particulate contaminate under or in any paint film that shows up as a raised bump of the cured paint film.

Probable Cau	ISE
Material	
Process	Dirt on parts as received
	• Dirt created by repairing SMC defects
	• Dirt on the paint rack that is not washed off
	• Dirt, hair, fibers, etc. from workers
	Improper paint shop cleanliness
	• De-ionized rinse out of spec
Tooling	
Corrective Ac	tion
Material	
Process	Installation of appropriate power washer
	Automate paint operations
	<ul> <li>Proper maintenance of paint equipment and paint booth</li> </ul>
	• Remove and clean overspray on the paint racks per agreed-upon schedule
	Analyze dirt particles to accurately determine source
	Clean overhead conveyor
	Improve paint shop cleanliness procedures
Tooling	



# **Dull Surface**

Loss of gloss on o	verall part surface
Probable Cause	
Material	High shrinkage
Process	• Under cure
	Loss of pressure
Tooling	Unacceptable tool surface
<b>Corrective Action</b>	
Material	Check for catalyst level
	Check resin reactivity
	Select different shrink additives or levels
Process	Increase mold temperature
	Increase cure cycle
	Increase molding pressure
	Maintain constant material pressure in press
Tooling	Polish and buff tool surface
	Chrome plate tool surface



#### **Ejector Cracks**

Ejector cracks are small, visible surface cracks on the cavity side surface of the molded part. These are often found on the opposite side of the part above an ejector pin. A crack located on the surface of the laminate that does not extend completely through the substrate.

Probable Cause		
Material	Resin Reactivity	
Process	• The part is sticking to the core	
	• The part is under-cured	
	Cure time is too low	
	Mold temperature is too low	
	Insufficient release agent	
	• The ejector pin is placed in a poor location, too few fins or too small a diameter	
Tooling	Ejection system is too fast	
	Blocked air to popper passage (partial)	
	<ul> <li>Improperly sized air supply line to air popper</li> </ul>	
	Ejection system leading air popper blow off	
	Excess flash around ejection pin	
	<ul> <li>Undercuts along shear (acting as "hangers")</li> </ul>	
<b>Corrective Action</b>		
Material	Use less reactive catalyst	
Process	Check temperature and cure times	
	• Place ejector pins in areas least sensitive such as below ribs or bosses, increase	
	diameter or number of pins	
	Add vented ejector pins	
	<ul> <li>Verify correct load pattern weight</li> </ul>	
	<ul> <li>Add external mold release, mold one part, then discard that part</li> </ul>	
	Clean shear edges	
Tooling	Slow ejection system	
	Check mold for undercuts	
	<ul> <li>Alleviate stresses holding the part too tight to the core (undercuts, etc)</li> </ul>	
	Proper sequencing of air popper system	
	<ul> <li>Inspect mold for biased ejection, install flow control or dividers</li> </ul>	
	<ul> <li>If ejectors are on angled surface add skid grooves to top of ejector pin</li> </ul>	



#### **Fiber Pull**

Fiber Pull is a depression left by removing or loosening of fiberglass strands located near the surface of the laminate.

Probable Cause	
Material	Sticking
Process	Flash buildup on the by-pass
Tooling	• Worn by-pass
<b>Corrective Action</b>	·
Material	
Process	Add external mold release and clean by-pass
	Vary mold temperature differential (normally narrow the difference)
	Decrease by-pass opening
	Correct ejector action (are all ejector pins working)
	Slow ejector speed
Tooling	



#### **Fiber Tear**

Fiber tear is a s	surface defect caused by fibers tearing away part of the surface resin. These defects
Brobable Caus	
Material	
Process	Improper deflashing of the part
	• Eiector speed too fast
	Charge weight too high
	Mold temperature differential incorrect
	Molding pressure too high
	Molding viscosity too low
	• Shear edge temperature variance too liberal (causing excess flash/leakage)
	Molding press strip speed too fast
	Flow parallel to shears
Tooling	Improperly fit or worn shear edges
<b>Corrective Act</b>	ion
Material	
Process	Use sandpapers, file or automatic router to deflash instead of a knife
	<ul> <li>Closer inspection of punched and drilled holes</li> </ul>
	• Use high technology process such as router, water jet, laser or ultrasonics to
	perform deflash, punch and drill operations
	<ul> <li>Verify correct load pattern weight</li> </ul>
	<ul> <li>Verify appropriate temperature differential between core and cavity</li> </ul>
	<ul> <li>Verify appropriate molding temperature</li> </ul>
	Slow ejector speed
	<ul> <li>Adjust charge to minimize flow parallel to shears</li> </ul>
Tooling	Maintain proper shear edge on molds to minimize flash



#### **Finger Tracks**

Finger tracks are shallow groves in the surface that show up after prime or top coat. These grooves are usually the width of a finger.

Probable Cause

Material	
Process	• Sanding the surface without a block or backup pad. The pressure directly under
	the fingers removes more material than between the fingers and leaves tracks
	that show up on the painted surface
	• It is generally accepted that the eye can detect surface depressions of 0.0004
	inches or greater over a one-inch span
Tooling	
<b>Corrective Action</b>	
Material	
Process	Always use block or pad when sanding the surface
	<ul> <li>Develop sanding and feathering techniques that blend surface changes over</li> </ul>
	large areas
	Use 400 grit or finer sandpaper
Tooling	



#### **Fish Eye**

A fish eye is a circular or elliptical depression in the primer. There is not any penetration into the substrate. Fish eyes are usually caused by some type of surface contamination

Probable Cause	
Material	
Process	• Oil, grease or silicone contamination in paint system, air feed, paint conveyor
	line or in the paint itself
	<ul> <li>Rags containing oil or oil byproducts</li> </ul>
	Excess mold release at source
	Insufficient cleaning of the part
	Overspray of primer
	Mismatch of solvent with paint or prime system
	• Ensure parts are not being sprayed or dripped on at press by hydraulic oils (if
	so, with 50% IPA and 50% DI water)
Tooling	
<b>Corrective Action</b>	n
Material	
Process	• Do not use silicone-containing hand creams or lubricants during handling at
	press-side or bonding
	<ul> <li>Properly installed power washer for all SMC parts</li> </ul>
	Proper maintenance of equipment (filters, etc.)
	<ul> <li>Ensure proper use of oils and lubricants in the paint shop</li> </ul>
	Proper QC procedures on all paint materials
	<ul> <li>Fish eye reducing additives to paint are available.</li> </ul>
Tooling	



# **Flow Marks**

Flow marks is the visual orientation of fiberglass strands on the part surface		
Probable Cause		
Material		
Process	• Flow condition	
Tooling	• Tool design	
Corrective Action		
Material	<ul> <li>Evaluate molding viscosity effect</li> </ul>	
	Select different shrink additives or levels	
Process	Decrease material flow distance	
	Relocate charge pattern	
	Increase press closure rate	
Tooling	Change part wall thickness	



#### **Fractures**

A Fracture is a structural failure in a part which extends complete through the substrate		
Probable Cause		
Material	Insufficient glass reinforcement	
	<ul> <li>Sticking or wedging of part in mold</li> </ul>	
Process	<ul> <li>Mechanical hang-up from flow related knit lines</li> </ul>	
	• Rough handling	
	<ul> <li>Poor material flow pattern around mash-offs, etc.</li> </ul>	
	<ul> <li>Charge pattern change by adding small pieces to produce proper weight</li> </ul>	
	<ul> <li>In process racks not used or poor quality secondary fixtures</li> </ul>	
	Press opens askew	
	<ul> <li>Poor part design (if every part is cracked)</li> </ul>	
	Improper combination of drill speed and feed rate	
	• Shipping damage	
	Heavier shear on one edge	
	Dull drill bit or worn out sleeve	
	<ul> <li>Undercut at parting lines or undercut in the mold</li> </ul>	
	• Shears too tight	
	Cure time too short	
	Parallelism of ejectors	
Tooling	<ul> <li>Improperly-designed secondary fixtures or tooling</li> </ul>	
<b>Corrective Action</b>		
Material	• Control SMC sheet weight to allow use of automatic cutting of charge patterns	
	<ul> <li>Use QC on SMC glass content</li> </ul>	
	Check SMC flow	
Process	<ul> <li>Train workers in proper handling techniques</li> </ul>	
	<ul> <li>Reduce material flow distance (reduce the flow front)</li> </ul>	
	<ul> <li>Design charge pattern to minimize improper flow behavior</li> </ul>	
	<ul> <li>Do not use make-up pieces in charge patterns</li> </ul>	
	<ul> <li>Properly support part in shipping containers</li> </ul>	
	<ul> <li>Evaluate proper paint rack design</li> </ul>	
	Check shears	
	Change drill bit or sleeve	
	<ul> <li>Eliminate any undercuts in the mold</li> </ul>	
	Increase cure time	
	Slow ejector speed	
	Vary mold temperature differential	
	Add vented ejector pins	
	Relocate charge	
Tooling	• Design secondary fixtures so that they do not induce stress in the part	
	Draw polish shear edges in the cavity	
	Use parallelism control on the press	
	<ul> <li>Change part wall thickness</li> </ul>	



# Gouge

Causa	
an be several thousands of an inch deep.	
is a long, deep depression in the surface, severe enough to require a repair	procedure.

Probable Cause	
Material	
Process	<ul> <li>Rough handling</li> <li>Improperly designed secondary fixtures (not padded in all necessary areas)</li> <li>Mold defects on edges or flash stuck to shear edge</li> <li>Shipping racks lack necessary padding</li> <li>No use of in-process racks (parts are stacked on each other)</li> </ul>
	<ul> <li>Square edge on part at mating surface with adjacent parts</li> </ul>
Tooling	
<b>Corrective Action</b>	
Material	
Process	<ul> <li>Investigate potential source for gouges in process and correct</li> <li>Train workers in proper handling techniques</li> <li>Design secondary fixtures properly and coat them with soft materials to absorb shocks</li> <li>Preventative maintenance on molds and fixtures</li> <li>Periodically clean flash on shear edges</li> <li>Improve shipping rack repair procedures</li> <li>Utilize transfer lines and other hands off processing techniques</li> <li>Repair using approved repair procedure</li> </ul>
Tooling	



#### **Hanging Fibers**

Hanging fibers are glass fibers that are left hanging from the part after a deflashing, hold piercing or drilling operation. These fibers cause dirt to be carried into the paint shop.

Probable Cause		
Material		
Process	• Dull or improperly fit secondary tooling (bits, mash-offs, punches, etc.	
	<ul> <li>Improper sanding to remove fibers</li> </ul>	
Tooling	Dull deflashing tool	
Corrective Action		
Material		
Process	Closer inspection of pierced and drilled holes	
	• Use high technology process such as router/drill bit design, water jet, laser or	
	ultrasonics to perform deflash, punch and drill operations.	
Tooling	• Proper maintenance program need for molds, pierce dies and secondary tools.	



#### **Knit Lines**

Knit line is a term for the molding condition which relates to oriented fiber patterns in the molded part. The knit line usually occurs at the edges or corners of the part furthest from the charge placement position. It is an extremely weak area in the molded part resulting from two flow fronts meeting.

Probable Cause	
Material	
Process	Flow fronts from different charge pattern pieces
	Too far of a distance for the SMC to flow
	Charge pattern position
	Incorrect rate of tonnage build
	• Spiral flow of SMC to high/low
	Mold temperatures too high
Tooling	Mold design (deep vertical walls), etc.
<b>Corrective Action</b>	
Material	
Process	Appropriate load placement
	Proper press closure
	Proper load pattern dimensions
	Consistent tonnage build
	Check oil level in press
	<ul> <li>Place charge directly over critical or knit line area if possible</li> </ul>
	<ul> <li>Decrease closure speed (reduce amount of orientation)</li> </ul>
	Eliminate separate charges if possible
	Verify correct molding temperature
Tooling	Optimize mold design for best flow conditions



# Laking

Laking is an irregular dull area on the surface of the part. The dull area may be associated with porosity. Laking can also be noticed after prime as "soak-in"

Probable Cause	
Material	Differential shrinkage
Process	• Too low a pressure on the part during molding (usually on vertical walls
	Molding on stops
	Load pattern weight too low
	Under-cured part
	Cold spots on mold
Tooling	
<b>Corrective Action</b>	
Material	Select different shrink additives and/or levels
Process	Maintain pressure on material during molding
	• Do not mold on stops or flash
	<ul> <li>Verify load weight is correct and not too low</li> </ul>
	Verify mold temperatures
	Increase pressing speed
Tooling	Equip press with parallelism control



#### **Mold Marks**

A mold mark is a l	ump, depression or line that occurs in the same location of every part due to a	
damaged mold		
Probable Cause		
Material		
Process		
Tooling	<ul> <li>Damage to the cavity of the mold due to insufficient protection</li> </ul>	
	<ul> <li>Stuck parts that require scraping off the mold</li> </ul>	
	Improper tools used to clean the mold	
	<ul> <li>Thickness variation flowing thin to thick causing tool wear</li> </ul>	
	Hard metal object molded into part causing mold damage	
<b>Corrective Action</b>		2
Material	Proper QC of SMC materials will reduce the sticking of parts	
Process		
Tooling	<ul> <li>Repair molds as required</li> <li>Regular maintenance program for molds</li> <li>Make sure all cutting utensils are made from soft materials that will not damage the mold surface</li> <li>Make sure all employees use only copper, brass, wood or plastic tools to scrape the mold surface</li> <li>Wire down all loose items on the cutting table and loading/unloading equipment</li> <li>Protect mold surface in transport and storage</li> <li>Automation should be constructed from aluminum or other soft materials</li> </ul>	



#### **Molded Poly**

Irregular shaped, small depressions on the surface of a part shaped like carrier film chips, but recessed into the substrate. These depressions are normally the colour of the film.

Probable Cause	
Material	
Process	<ul> <li>Pieces of carrier film that are molded into the SMC part</li> </ul>
Tooling	
<b>Corrective Action</b>	
Material	
Process	• Make sure that all carrier film is removed from the charge, especially when
	automatic film stripping is not used.
	Proper repair procedure required
	• Frequent changing of blades to ensure clean cuts
	Check for proper slitter cutter alignment to shear guide. Improper alignment
	will cause a small strip to adhere to the edge of the SMC unnoticed.
Tooling	



#### Non-Fill

A non-fill is a severe void in the laminate. It is an incomplete part that must be scrapped	
Probable Cause	
Material	
Process	• Tonnage too low
	<ul> <li>Mold temperatures too high</li> </ul>
	<ul> <li>Not enough SMC charge weight</li> </ul>
	Molding on stops
	<ul> <li>Press closure too slow (tonnage build rate too slow)</li> </ul>
	<ul> <li>Mold temperatures of cavity and core are too close (no flash)</li> </ul>
	• Flash/debris on the mold shears/stops
	<ul> <li>SMC charge sits on mold too long before closure</li> </ul>
	• SMC charge has to flow too far
Tooling	Tool or platen deflects
<b>Corrective Action</b>	
Material	Decrease molding viscosity
	Use less reactive catalyst
Process	<ul> <li>Verify parameters to control plan/process sheet (tonnage, load pattern, load</li> </ul>
	placement, temperature, closure speeds)
	Check SMC spiral flow
	Verify molding off stops
	Clean mold shears/stops
	Check for deflection
	Monitor SMC viscosity build
	<ul> <li>Verify weight scales are correct</li> </ul>
	Increase molding pressure
	Increase closure speed
	<ul> <li>Ensure charge weights are balanced</li> </ul>
	Decrease material flow distance
	Check oil level in press
	<ul> <li>Vent ejector pins and/or add vented ejector pins</li> </ul>
	Shorten tool load time
Tooling	• Blend core half to reduce thin to thick flow restrictions in area of non-fill



#### **Paint Sags**

A sag is excess	paint on a part that shows itself as a hump or ripple that distorts the surface.
Probable Cause	e
Material	
Process	Oven temperature too low
	<ul> <li>Viscosity of paint too low, too much solvent</li> </ul>
	• Film build too thick
	<ul> <li>Spray gun too close to part being painted</li> </ul>
	Inconsistent sanding of parts to be reworked (causing sags when painting with
	electrostatics)
Tooling	
<b>Corrective Acti</b>	on
Material	
Process	QC paint viscosity on each shift
	Monitor and control ultimate over temperature and heat up rate
	Do not allow painters to get ahead or behind job sequence
	Instruct painters on proper spray techniques
	Preventative maintenance of spray equipment
	Implement automatic paint spraying equipment
	Verify appropriate air pressure
	Verify appropriate paint pressure
	Increase distance between part and gun
	Use more coats of paint to get desired film build
	Thoroughly scuff sand reworks prior to paint.
Tooling	



#### Porosity

Porosity is an observable or unobservable condition in any part. It consists of a cluster of holes that usually occurs when trapped air escapes during the molding process. This cluster usually covers an area no larger than a quarter, but can be larger, and can occur as a single hole. Unfilled porosity creates a crater-type condition on a top coated part

Probable Cause	
Material	• Excess styrene loss
Process	<ul> <li>Insufficient flow of the SMC; too large/small a charge pattern</li> </ul>
	• Pre-gel
	Flash on shear edge prevents adequate venting of gasses
	Insufficient pressure on material during molding
	Improper press closure speed
	Mold temperature too high
	Vacuum too low; improper vacuum cycle
	Undercure
	Low charge weight
	Adding small SMC pieces to charge pattern
	• Too many plies
	Molding on stops
	Moisture contamination
Tooling	
<b>Corrective Action</b>	
Material	Evaluate viscosity level
	Verify material is not dried out
Process	<ul> <li>Verify vacuum amount and timing</li> </ul>
	Verify load pattern location, size, thickness
	Verify appropriate press closure speeds
	Verify appropriate temperatures
	Verify molding off stops
	Make sure mold shears are clean
	Increase material flow distance
	Minimize number of plies in charge
	Check charge weight
	Check molding pressure
	Clean mold stops
Tooling	Change part wall thickness



#### Pre Gel

Pre-gel causes localized areas of dull, rough, porosity, usually with discoloration		
Probable Cause		
Material	Too reactive resin	
	Too reactive catalyst	
Process	Slow closure rate	
Tooling		
Corrective Action		
Material	Check resin reactivity	
	Use less reactive catalyst	
Process	Shorten tool loading time	
	Increase press closure rates	
	Decrease mold temperature	
Tooling		



#### **Resin Rich**

An area in the part where fiberglass strands content is low.		
Probable Cause		
Material	Resin is not carrying fiberglass strands	
Process		
Tooling		
Corrective Action		
Material	<ul> <li>Increase material molding viscosity</li> </ul>	
Process	Relocate charge pattern	
	Decrease material flow distance	
	Slow pressure closure rate	
Tooling		



#### **Rib, Pin and Boss Readout**

A surface depression located over ribs, bosses, ejector pins or thick sections of the part that appear	
as a lighter color r	resulting in read through.
Probable Cause	
Material	
Process	Lack of material flow
	Lack of cavity/core temperature differential
	• Lack of a tonnage "bump" (decrease molding pressure after 30 seconds into
	cycle)
Tooling	
<b>Corrective Action</b>	
Material	
Process	Increase material flow distance (do not load over a boss)
	Increase mold temperature differential (the hotter appearance side will gel
	slightly faster and will reduce the amount of sink)
	Reduce tonnage after mold fill (high tonnage held through the cure cycle
	increases sink. Reduce tonnage by 25% to 30% after 30 seconds.
Tooling	



# Ripple

Severe short-term waves in the SMC, almost always on the edge of a part or vertical walls.	
Probable Cause	
Material	Improper viscosity
	Material too old and will not flow properly
	Higher paste shrinkage
	Improperly maturated SMC
	• Extremely high-flowing SMC
Process	Inconsistent force on the material during molding
	Charge pattern placed or cut improperly
	Temperature of mold too high or dropped temperature zone of mold
	Improper closure speed
	Abrupt thick-to-thin flow condition
	Reflow of material due to non-parallel closure (leveling)
Tooling	Mold not centered to press platen
	Flow turbulence resulting from tool design
<b>Corrective Action</b>	
Material	Investigate viscosity of paste
	Verify SMC is within appropriate spiral flow
	Investigate past shrinkage
Process	Increase tonnage
	Decrease material flow distance
	Verify charge weight
	Verify molding off stops
	Monitor and control mold temperatures to specs
Tooling	May need to offset mold
	Modify tooling



# Sand Through

A sand through is	a break through the primer surface resulting from a sanding operation.
Probable Cause	
Material	
Process	<ul> <li>Localized sanding that is deeper and more severe than is necessary (finger sanding)</li> <li>Tipping power sander to cut deeper in one area to remove dirt or other localized defects</li> </ul>
	Sanding with too course a sandpaper
Tooling	
<b>Corrective Action</b>	
Material	
Process	<ul> <li>Always block sand defects</li> <li>Repair mold when mold marks appear to minimize the amount of sanding</li> <li>Goal is to avoid using sandpaper</li> <li>Eliminate use of power sanders</li> <li>Use only 400-grit or finer sandpaper</li> </ul>
Tooling	



#### **Sander Scratches**

 Scratches in the substrate result from a sanding operation. These scratches usually appear as very fine circular scratches.

 Probable Cause

 Material

 Process
 • Sanding curved areas of part with a flat sander

 • Improper grit size paper

- Sanding Class "A" surface to remove die marks
- Repair procedures for all defects
  - Poor flash removal methods which require additional sanding
- Excessive loading of sandpaper with sanding debris

Tooling	
<b>Corrective Action</b>	
Material	
Process	Establish specification describing grit size for specific operations
	Hand sand curved areas that require sanding
	Repair die marks on mold, not on parts
	Automate flash removal to eliminate error
	<ul> <li>Specify paper grit size for every repair method</li> </ul>
	Specify sandpaper change interval
	Clean debris from unloading fixture or racks
Tooling	



#### Scratch

A scratch is simila usually be feathe	r to a gouge, but is not deep enough to require fill repair material. A scratch can r sanded out.
Probable Cause	
Material	
Process	Rough handling
	• Improperly designed secondary fixtures (not padded in all necessary areas)
	Mold defects on edges or flash stuck to shear edge
	Shipping racks lack necessary padding
	No use of in-process racks (parts are stacked on each other)
	Square edge of part a mating surface with adjacent parts
Tooling	
<b>Corrective Action</b>	
Material	
Process	Train workers in proper handling techniques
	• Design secondary fixtures properly and coat them with soft materials to absorb shocks
	• Design secondary fixtures properly and coat them with soft materials to absorb shocks
ł	Preventative maintenance on molds and fixtures
ł	Periodically clean flash on shear edge
ł	Improve shipping procedure and monitor part quality
ł	Improve shipping rack repair procedures
ł	Utilize transfer lines and other hands-off processing techniques
ł	Repair using approved repair procedure
Tooling	



# Separation (Phasing)

An area of high thermoplastic content resulting in non-uniformity of color		
Probable Cause		
Material	Separation of the thermoplastic resin from polyester	
Process		
Tooling		
Corrective Action		
Material	<ul> <li>Increase molding viscosity</li> </ul>	
	Select different shrink additives and/or levels	
Process	Shorten die loading time	
	Increase material flow distance	
	Decrease molding pressure	
	Decrease molding temperature	
Tooling		



# Scumming

Dulling or streaks in the part (generally transfers a similar pattern on the tool surface).		
Probable Cause		
Material	Incompatible resin additives	
Process	<ul> <li>Internal mold release not functioning at the mold temperature</li> </ul>	
Tooling		
Corrective Action		
Material	Use greater viscosity material	
	Select different shrink additives and/or levels	
Process	Increase mold temperature	
	Increase material flow distance	
	Shorten tool loading time	
Tooling		



#### **Sink Marks**

A sink is a depression on the part surface that will normally occur over ribs or bosses. It is possible to get a sink on the edge of a flanged part. Sinks can range in depth from 0.0004 to several thousands of an inch anywhere along a rib or boss.

Probable Cause	
Material	Poor glass orientation
	• Excess shrinkage of the SMC over a thick section
Process	Inadequate molding pressure
	Temperature variations due to variable thickness
Tooling	Improper rib design
<b>Corrective Action</b>	
Material	Select different shrink additives and/or levels
Process	• Flow material from a thick section to a thin section so as not to create surge
	flow patterns in localized areas (the surge flow orients glass fibers perpendicular
	to adjacent areas which shows up as a sink).
	• Cross sectioning the wall section may be necessary to prove a thin-to-thick
	flow condition
	Control aspect ratio of rib and boss (depth-to-thickness ratio); rib should not
	be more than 0.075" thickness of attached wall
	<ul> <li>Place ribs and bosses behind design lines</li> </ul>
	Mold off stops
	<ul> <li>If sink is over a "boss", reduce mass by having a long cored hole</li> </ul>
Tooling	Modify tooling



#### Sticking

Sticking occurs when the part adheres to the cavity or core and is not easily released or results in a crack upon removal.

Probable Cause	
Material	Release problem with the SMC
	<ul> <li>SMC shrinkage control is incorrect</li> </ul>
Process	Core is too rough
	Charge weight is excessive
	Undercuts on cavity or core
	Part is under-cured
	Temperature spread on dies too close
	Press strip is too fast
	Contaminated mold surface (oils, dirt, etc)
Tooling	Mold surface is corroded
<b>Corrective Action</b>	
Material	Check for SMC release
	Check SMC shrinkage data
Process	Slow strip speed
	Clean mold surface/run break-in material
	Add external mold release
	Increase cycle time
	Increase mold temperature
Tooling	<ul> <li>Evaluate mold for undercuts and remove where necessary</li> </ul>
	Check chrome plating wear
	Polish tool surface
	Pyramid charge in the center of the tool



# **Streaking (Abrasion)**

Dark areas, directional, in line of flow, found in pigmented parts and is generally located over fiberglass strands		
Probable Cause		
Material		
Process		- 14 C
Tooling	Tool abrasion or scuffing	
<b>Corrective Action</b>		
Material	Check raw material	
	Use greater viscosity material	
	Select different shrink additive or level	
Process	Relocate charge pattern	
Tooling	Polish or buff out tool surface	
	Chrome plate tool surface	



#### **Surface Waviness**

Short term waviness has wave lengths for ¼ to one inch long. Long term waviness has wave lengths from one to five inches. Waviness causes distortion of straight lines on the Class "A" surface and is most readily observed on a painted part.

Probable Cause	
Material	
Process	Improper spiral flow of SMC sheet when molded
	<ul> <li>Inconsistent force on the material during molding</li> </ul>
	Parts molded with improper pressure
	Charge pattern cut or placed improperly
	<ul> <li>Flow interrupters (mash-offs, core pins, part geometry) in mold</li> </ul>
	Partial charge
	• Improper bonding temperature (Undercure) which can cause bond readout,
	causing waviness.
Tooling	
<b>Corrective Action</b>	
Material	
Process	Monitor spiral flow for appropriate values
	<ul> <li>Use proper pressure to mold material</li> </ul>
	Remove flow interrupters from mold
	Monitor viscosity of paste
	Monitor and control mold temperatures to specs
	<ul> <li>Refer to design guide for allowable thick-to-thin transition</li> </ul>
	<ul> <li>Verify closure speeds, load pattern (location, size) and leveling</li> </ul>
	Verify molding off stops
	Monitor viscosity of paste
Tooling	



#### Undercure

Undercure is an incomplete cure or bake cycle of the SMC in the mold. The part is often extremely smoky, very dull and can exhibit blown bosses or ribs. This part is scrapped.

Probable Cause		
Material	Unreactive resin	
	Incorrect cure chemistry	
Process	Low temperatures and/or short cycle time	
	Loss of tonnage	
Tooling		S
<b>Corrective Action</b>		
Material	Check SMC for cure time	
	Check resin reactivity	
Process	Check mold cold spots or bad stream lines and regulators	
	Verify cure times	
	Verify tonnage via parameter sheet	
Tooling		



# Warpage (Dimensional Error)

Dimensional error	r is the failure of the part to fit the checking fixture or to meet print tolerances due
to Warpage, shrin	k, expansion or tooling error.
Probable Cause	
Material	Out of spec material
Process	Uneven cure
	<ul> <li>Excessive stress on the part when unloading or bonding</li> </ul>
	<ul> <li>Not allowing the part to cool on fixture long enough</li> </ul>
	<ul> <li>Variable charge pattern or placement</li> </ul>
	Improper expansion factor in tool for approved material
	<ul> <li>Improper thermal expansion material molded in approved mold</li> </ul>
	Improperly designed paint fixture
	Degree of cure – bond line
Tooling	Tool temperatures not within spec
<b>Corrective Action</b>	
Material	Verify SMC for proper shrinkage
Process	<ul> <li>Use heat management design of mold to permit consistent curing of part</li> </ul>
	Proper placement of ejector pins reduces demolding stress
	Evaluate process for sufficient cooling time
	• Control charge pattern by area, not weight. When possible use laser light or
	automation to permit consistent charge placement
	<ul> <li>Design paint fixtures to properly support part during baking</li> </ul>
	<ul> <li>If bonded assembly, review bonding process</li> </ul>
	Verify cure time versus tool temperature capability of maintaining correct
	temperature through consecutive moldings.
	Decrease material flow distance
	Increase cure time or temperature
	Vary mold temperature differential
	Increase charge pattern
	Verify mold temperatures
Tooling	• Proper mold design to ensure that the part does not stick to core or cavity
	• Work with design engineers early in program so that mold is constructed using
	expansion factors of the newer-technology materials



# Water Spots

Circular spots on the painted surface usually in groups. These spots are usually depressions with a		
raised ring around the edge. Water spots can cause paint failure of top coats/		
Probable Cause		
Material		
Process	<ul> <li>Failure to fully dry the part after a wash operation</li> </ul>	
	<ul> <li>Failure to sue a DI water rinse after wash</li> </ul>	
	<ul> <li>Failure to clean and filter DI water to meet specifications</li> </ul>	
	<ul> <li>Part designs which trap water in pockets</li> </ul>	
	<ul> <li>Failure to use a rinse additive which ensures a water break-free surface</li> </ul>	
Tooling		
<b>Corrective Action</b>		
Material		
Process	<ul> <li>Dry parts thoroughly after all wash operations</li> </ul>	
	• Design drain holes into parts when necessary to prevent the accumulation of	
	water during the wash cycle	
	QC rinse water to specs	
	<ul> <li>Use and maintain a rinse additive after parts washing</li> </ul>	
Tooling		



#### White Spots

A general light separation. Th	t or whitened area on a pigmented surface that occurs as a result of thermoplastic ne problem is associated with pitting occurring in the white spotted area.
Probable Caus	se
Material	<ul> <li>Low viscosity builds of SMC through maturation</li> </ul>
	<ul> <li>Thermoplastic incompatibility with SMC formulations</li> </ul>
	Flow restrictions
Process	
Tooling	
Corrective Act	tion
Material	Verify day 1 viscosity
	Record occurrence and roll yardage when problem occurs
	Record material rates and lot number when problem occurs
	Verify spiral flow of material
Process	Verify load pattern is correct according to engineering specification
	Reduce die coverage to allow for increased flow
Tooling	